WNSC2D051700DT2

Silicon Carbide Diode

Rev.01 - 14 October 2026 Product data sheet

1. General description

Silicon Carbide Schottky diode in a TO252-2L plastic package, designed for high frequency, high efficiency systems.

2. Features and benefits

- Highly stable switching performance
- High forward surge capability I_{FSM}
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant
- High junction operating temperature capability ($T_{j(max)}$ = 175 °C)

3. Applications

- Switching mode power supplies
- UPS & energy storage systems
- PV inverter and MPPT circuit
- Battery formation systems
- EV chargers
- Motor Drives

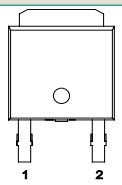
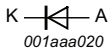
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V_{RRM}	repetitive peak reverse voltage			1700			V
I_F	continuous forward current	T_{mb} ≤ 158 °C; DC; Fig. 2		5			A
T_j	junction temperature			-55 to 175			°C
Symbol	**Parameter**	**Conditions**	**Notes**	**Min**	**Typ**	**Max**	**Unit**
Static characteristics							
V_F	forward voltage	I_F = 5 A; T_j = 25 °C; Fig. 5		-	1.42	1.60	V
		I_F = 5 A; T_j = 150 °C; Fig. 5		-	2.00	2.40	V
Dynamic characteristics							
Q_r	recovered charge	I_F = 5 A; dI_F/dt = 500 A/µs; V_R = 400 V; T_j = 25 °C; Fig. 7		-	13.6	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	K	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2D051700DT2	TO252-2L	WNSC2D051700DT26J	Reel	2500	TO252T-2L	19-Dec-2025

7. Marking

Table 4. Marking codes

Type number	Marking codes
WNSC2D051700DT2	WNSC2D05 1700DT2

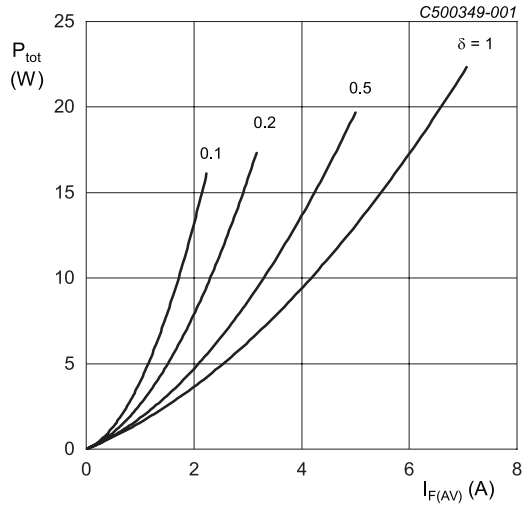
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8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			1700	V
V_{RWM}	crest working reverse voltage			1700	V
V_R	reverse voltage	DC		1700	V
I_F	continuous forward current	T_{mb} ≤ 158 °C; DC; Fig. 2		5	A
		T_{mb} ≤ 125°C; DC; Fig. 2		9.9	A
		T_{mb} ≤ 25°C; DC; Fig. 2		18.6	A
I_{FRM}	repetitive peak forward current	δ = 0.5; t_p = 25 µs; T_{mb} ≤ 125 °C; square-wave pulse		14.8	A
I_{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		72	A
		t_p = 10 µs; $T_{j(init)}$ = 25 °C; square-wave pulse		730	A
I^2t	I^2t for fusing	sine-wave pulse; $T_{j(init)}$ = 25 °C; t_p = 10 ms		25.92	A^2s
T_{stg}	storage temperature			-55 to 175	°C
T_j	junction temperature			-55 to 175	°C



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$
V_o = 1.290 V; R_s = 0.2647 Ω

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

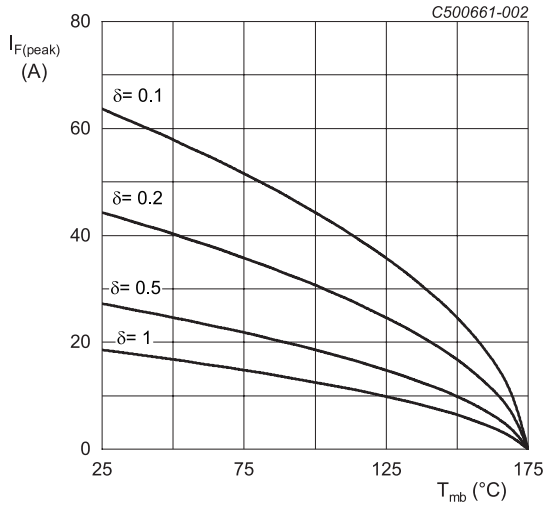


Fig. 2. Current derating as a function of mounting base temperature

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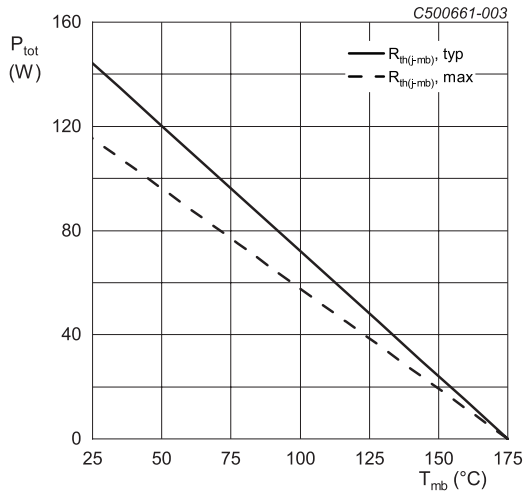


Fig. 3. Total power dissipation as a function of mounting base temperature

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9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 4		-	1.04	1.3	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	40	-	K/W

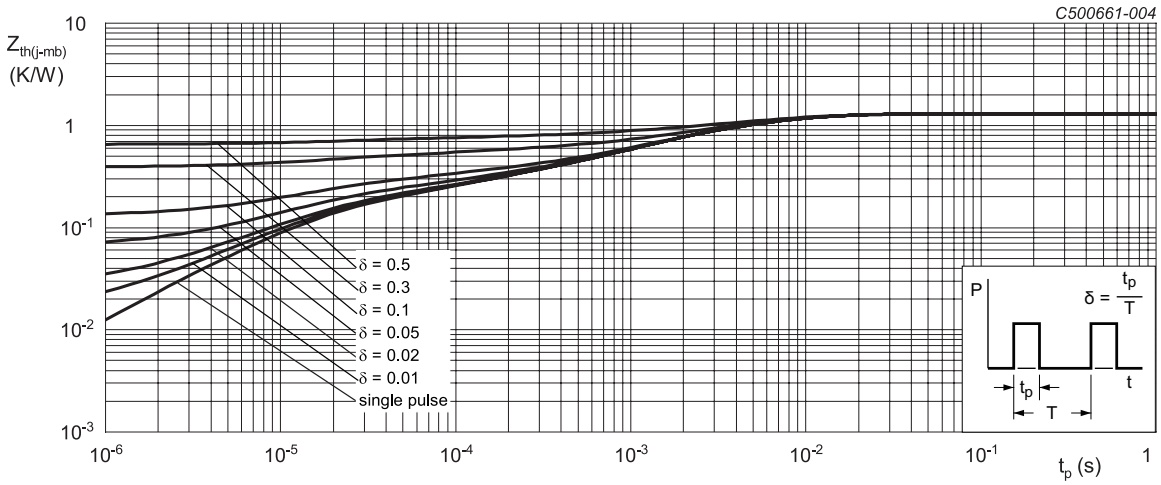


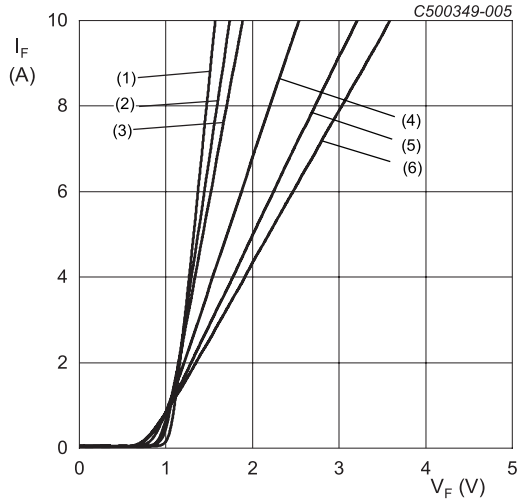
Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

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10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward current	I_F = 5 A; T_j = 25 °C; Fig. 5		-	1.42	1.60	V
		I_F = 5 A; T_j = 150 °C; Fig. 5		-	2.00	2.40	V
		I_F = 5 A; T_j = 175 °C; Fig. 5		-	2.10	2.60	V
I_R	reverse current	V_R = 1700 V; T_j = 25 °C; Fig. 6		-	1	15	µA
		V_R = 1700 V; T_j = 175 °C; Fig. 6		-	10	-	µA
Dynamic characteristics							
Q_r	recovered charge	I_F = 5 A; V_R = 400 V; dI_F/dt = 500 A/µs; T_j = 25 °C; Fig. 7		-	13.6	-	nC
C_d	diode capacitance	f = 1 MHz; V_R = 1 V; T_j = 25 °C		-	316	-	pF
		f = 1 MHz; V_R = 800 V; T_j = 25 °C		-	21	-	pF
		f = 1 MHz; V_R = 1700 V; T_j = 25 °C		-	19	-	pF
E_{as}	non-repetitive avalanche energy	I_R = 3.2 A; L = 10 mH; $T_{j(init)}$ = 25 °C		51	-	-	mJ



V_o = 1.290 V; R_s = 0.2647 Ω
(1) T_j = -55 °C; typical values
(2) T_j = 0 °C; typical values
(3) T_j = 25 °C; typical values
(4) T_j = 100 °C; typical values
(5) T_j = 150 °C; typical values
(6) T_j = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

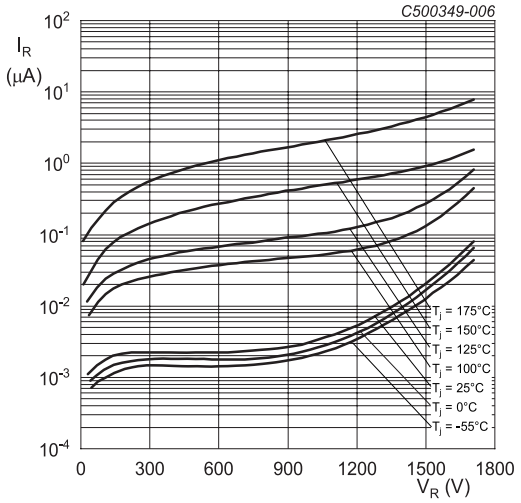


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

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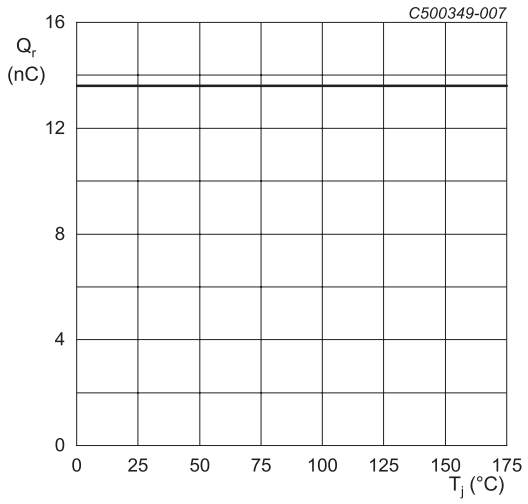
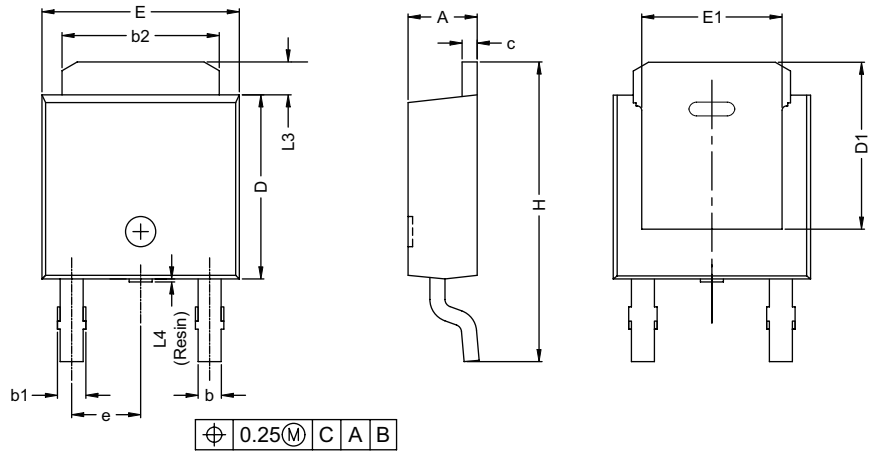


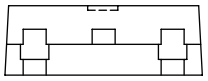
Fig. 7. Recovered charge as a function of junction temperature

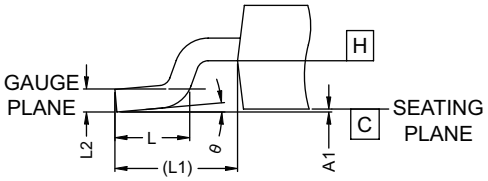
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11. Package outline

Plastic single-ended surface-mounted package (DPAK); 2 leads TO252-2L







SYMBOL	MIN.	MAX.	SYMBOL	MIN.	MAX.
A	2.18	2.39	E1	4.32	4.80
A1	0.00	0.13	e	2.29 BSC	
b	0.65	0.89	H	9.94	10.34
b1	0.76	1.13	L	1.45	1.78
b2	4.95	5.46	L1	2.74 REF	
c	0.46	0.61	L2	0.51 BSC	
D	5.97	6.30	L3	0.89	1.34
D1	5.21	5.70	L4	0.00	0.50
E	6.35	6.73	θ	0°	10°

NOTE：
1. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
2. All dimensions are in millimeters. Angles are in degrees.
3. All dimensions do not include mold flash or protrusion.
4. Radius on terminal is optional.

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